

IN THE SPECIFICATION

A. Please delete the current version of paragraph [0010] found in the Description of the Invention and replace it with the following substitute paragraph:

--[0010] One of the objects of the invention is to provide a material composition for packaging comprising (a) an epoxy resin and (b) a curing agent, wherein the mixing ratio by weight of said epoxy resin to said curing agent is in the range of from 0.7 to 1.1. --

B. Please delete the current version of paragraph [0012] found in the Description of the Invention and replace it with the following substitute paragraph:

--[0012] The material composition for packaging of the present invention comprises (a) an epoxy resin and (b) a curing agent wherein the mixing ratio by weight of said epoxy resin to said curing agent is in the range of from 0.7 to 1.1, preferably from 0.85 to 1.0. --

C. Please delete the current version of paragraph [0014] found in the Description of the Invention and replace it with the following substitute paragraph:

--[0014] The promoters which may be useful in the present invention are well known to persons skilled in the art. Non-limiting examples of the useful promoters include the salts, quaternaries quaternary ammonium salts, and imidazoles imidazole compounds and salts of 1,8-diazabicyclo[5.4.0]-undec-7-ene ("DBU") and a mixture thereof. The

quaternaries quaternary ammonium salts useful as promoters are well known to persons skilled in the art. Non-limiting examples of such quaternaries quaternary ammonium salts, include benzyl tributyl ammonium halides, benzyl trimethyl ammonium halides, benzyl tripropyl ammonium halides, phenyl tributyl ammonium halides, tetrabutyl ammonium halides, triphenyl benzyl ammonium halides, tetraethyl ammonium halides, and hexadecyl trimethyl ammonium halides.--

D. Please delete the current version of paragraph [0018] found in the Description of the Invention and replace it with the following substitute paragraph:

--[0018] The compositions with the formulas as shown in Table 1 below are prepared in accordance with the following procedure:

	Formula 1		Formula 2	
Epoxy	EPON 828	30	ERL-4221	20
	-	-	EPON 1510	10
Curing Agent	MHHPA	30	MHHPA	30
Promoter	<u>Quaternary</u> <u>QUATERNARY</u> <u>AMMONIUM</u> <u>SALTS</u>	0.3	<u>Quaternary</u> <u>QUATERNARY</u> <u>AMMONIUM</u> <u>SALTS</u>	0.3